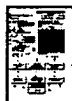




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JP5098372A2: AGE HARDENING SPECIAL COPPER ALLOY

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Country: **JP Japan**

Kind:

Inventor(s): **MIKAWA TSUNEAKI**

Applicant(s): **MIKAWA TSUNEAKI
OKUHARA MASAHIKO**
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Issued/Filed Dates: **April 20, 1993 / Oct. 8, 1991**

Application Number: **JP1991000287279**

IPC Class: **C22C 9/00;**

Abstract: **Purpose:** To provide a copper alloy for electronic parts improved in mechanical properties.

Constitution: The copper alloy can be obtained by incorporating, by weight, 0.1-5% nickel, 0.01-7% silicon, 0.01-10% iron, 0.01-7% titanium, and 0.001-1% boron into copper as a principal component. As compared with the conventional alloy, this age hardening special copper alloy is improved in electric conductivity, thermal conductivity, and mechanical properties, particularly hardness and elasticity.

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Family:

Patent	Issued	Filed	Title
US5215711	June 1, 1993	April 6, 1992	Age-hardening type special Cu alloy
JP5098372A2	April 20, 1993	Oct. 8, 1991	AGE HARDENING SPECIAL COPPER ALLOY
JP2904372B2	June 14, 1999	Oct. 8, 1991	
3 family members shown above			

Other Abstract Info: **CHEMABS 119(10)101485T CAN119(10)101485T DERABS C93-188438**

Foreign References: **(No patents reference this one)**



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